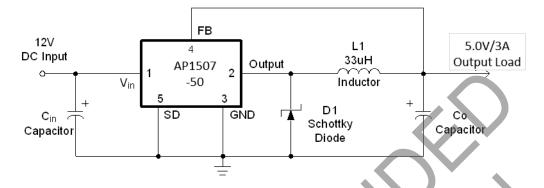
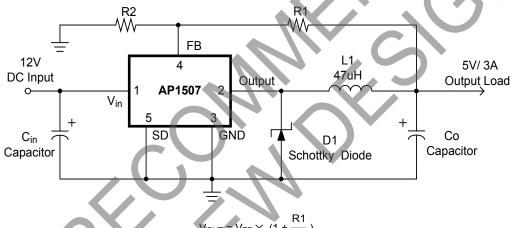


## **Typical Application Circuit**

#### (1) Fixed Type Circuit

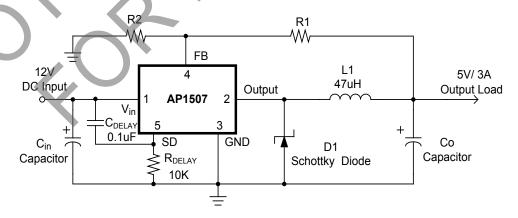


### (2) Adjustable Type Circuit



$$V_{OUT} = V_{FB} \times (1 + \frac{\cdots}{R^2})$$
  
R2  
 $V_{FB} = 1.23V, R2 = 1K \sim 3K$ 

### (3) Delay Start Circuit

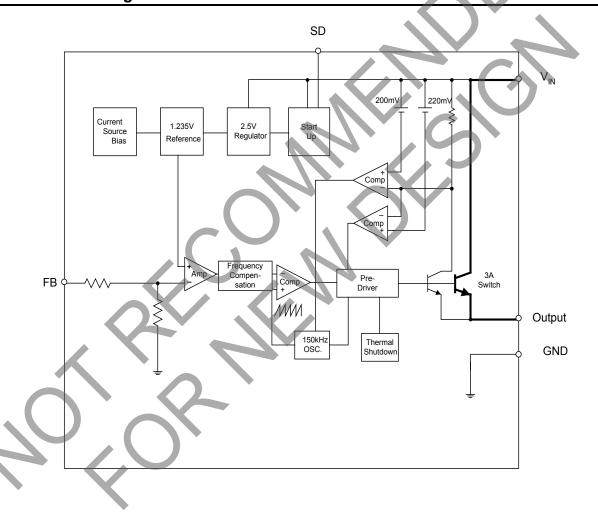




## **Pin Descriptions**

Pin Number	Pin Name	Description
1	$V_{IN}$	Operating Voltage Input
2	Output	Switching Output
3	GND	Ground
4	FB	Output Voltage Feedback Control
5	SD	ON / OFF Shutdown

# **Functional Block Diagram**





### Absolute Maximum Ratings (T<sub>A</sub> = +25°C) (Note 4)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage	+24	V
$V_{SD}$	ON/OFF Pin Input Voltage	-0.3 to +18	V
$V_{FB}$	Feedback Pin Voltage	-0.3 to +18	V
V <sub>OUT</sub>	Output Voltage to Ground	-1	V
$P_{D}$	Power Dissipation	Internally Limited	W
T <sub>ST</sub>	Storage Temperature	-65 to +150	°C
TJ	Operating Junction Temperature	-40 to +125	°C

Note

# Recommended Operating Conditions (T<sub>A</sub> = +25°C)

Symbol	Parameter		Min	Max	Unit
I <sub>OUT</sub>	Output Current		0	3	Α
V <sub>OP</sub>	Operating Voltage	7	4.5	22	V
T <sub>A</sub>	Operating Ambient Temperature		-20	+85	°C

<sup>4.</sup> Stresses greater than the Absolute Maximum Ratings specified above, can cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability can be affected by exposure to absolute maximum rating conditions for extended periods of time.



### Electrical Characteristics (All Output Voltage Versions)

Unless otherwise specified,  $V_{IN}$  = 12V for 3.3V, 5V, adjustable version and  $V_{IN}$  = 18V for the 12V version.  $I_{LOAD}$  = 0.5A Specifications with **boldface type** are for full operating temperature range, the other type are for  $T_J$  = 25°C.

Symbol	Para	meter	Condit	ions	Min	Тур	Max	Unit
I <sub>FB</sub>	Feedback Bias Current		V <sub>FB</sub> = 1.3V (Adjustable Version	n Only)	_	-10	-50 <b>-100</b>	nA
Fosc	Oscillator Frequency		_		127 <b>110</b>	150	173 173	kHz
F <sub>SCP</sub>	Oscillator Frequency of	of Short-Circuit Protect	When Current Lim $V_{FB} < 0.5V$ , $T_A = 25$		10	30	50	kHz
Vsat	Saturation Voltage		I <sub>OUT</sub> = 3A No Outside Circuit V <sub>FB</sub> = 0V Force Driv	ver On	-	1,4	1.6	V
DC	Max. Duty Cycle (ON)		V <sub>FB</sub> = 0V Force Driv		<u> </u>	100	-7	%
	Min. Duty Cycle (OFF)		V <sub>FB</sub> = 12V Force Dr	river Off		0	_	
I <sub>CL</sub>	Current Limit		Peak Current No Outside Circuit V <sub>FB</sub> = 0V Force Driv		3.6	4.5	5.5 6.5	Α
I <sub>LEAK</sub>	Output = 0V	Output Leakage Current	No Outside Circuit V <sub>FB</sub> =12V Force Dri			_	-200	μA
	Output = -1V	Current	V <sub>IN</sub> = 22V			-5	_	mA
IQ	Quiescent Current		V <sub>FB</sub> = 12V Force Dr	river Off	//	5	10	mA
I <sub>STBY</sub>	Standby Quiescent Current		ON/OFF Pin = 5V V <sub>IN</sub> = 22V		_	70	150 <b>200</b>	μΑ
V <sub>IL</sub>	ON/OFF Pin Logic Input Threshold Voltage		Low (Regulator ON High (Regulator OF		 2.0	1.3	0.6	V
I <sub>H</sub>	ON/OFF Pin Logic Input Current		V <sub>LOGIC</sub> = 2.5V (OFF	(-)	_	_	-0.01	
ΙL	ON/OFF Pin Input Current		V <sub>LOGIC</sub> = 0.5V (ON)		_	-0.1	-1	μΑ
θЈΑ	Thermal Resistance		TO252-5 Junction to Case		_	10	_	°C/W
θ <sub>JC</sub>	Thermal Resistance (Copper Area of Appro	oximately 2cm × 2cm)	TO252-5 June	ction to Ambient	_	50	_	°C/W



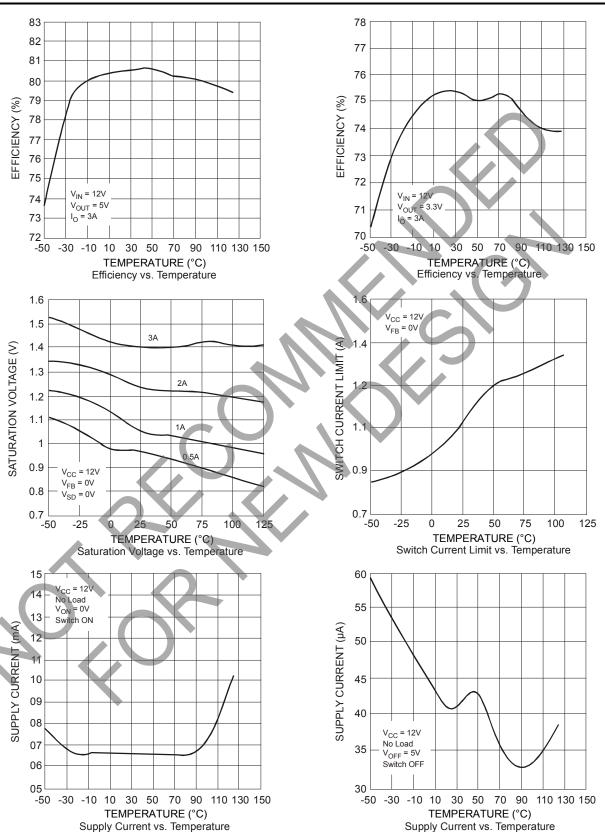
## Electrical Characteristics (continued) (All Output Voltage Versions)

Specifications with **boldface type** are for full operating temperature range, the other type are for  $T_J$  = +25°C.

_	Symbol	Parameter	Conditions	V <sub>MIN</sub>	Тур.	V <sub>MAX</sub>	Unit
AP1507-ADJ	$V_{FB}$		$5V \le V_{IN} \le 22V$ $0.2A \le I_{LOAD} \le 3A$ $V_{OUT}$ Programmed for $3V$	1.193 <b>1.18</b>	1.23	1.267 <b>1.28</b>	٧
	η	Efficiency	V <sub>IN</sub> = 12V, I <sub>LOAD</sub> = 3A	_	74	7	%
AP1507-3.3V	V <sub>OUT</sub>	Output Voltage	$5.5V \le V_{\text{IN}} \le 22V$ $0.2A \le I_{\text{LOAD}} \le 3A$	3.168 <b>3.135</b>	3.3	3.432 <b>3.465</b>	٧
	η		V <sub>IN</sub> = 12V, I <sub>LOAD</sub> = 3A	_	75	_	%
AP1507-5V	V <sub>OUT</sub>	Output Voltage	$8V \le V_{IN} \le 22V$ $0.2A \le I_{LOAD} \le 3A$	4.8 <b>4.75</b>	5	5.2 <b>5.25</b>	٧
	η	Efficiency	V <sub>IN</sub> = 12V, I <sub>LOAD</sub> = 3A	7	80	-	%
AP1507-12V	V <sub>OUT</sub>	Output Voltage	15V ≤ V <sub>IN</sub> ≤ 22V 0.2A ≤ I <sub>LOAD</sub> ≤ 3A	11.52 11.4	12	12.48 <b>12.6</b>	V
	n	Efficiency	V <sub>IN</sub> = 16V, I <sub>LOAD</sub> = 3A	_	89	<u> </u>	%

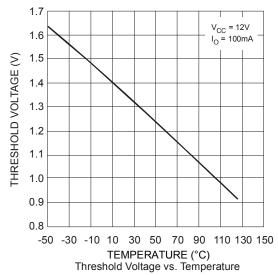


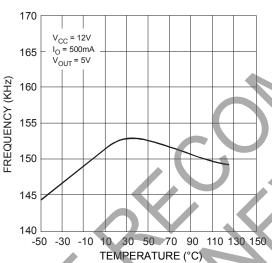
# **Typical Characteristics**

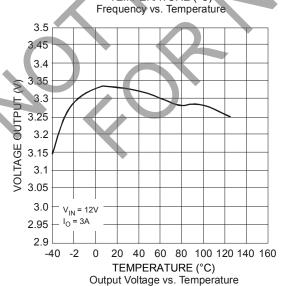


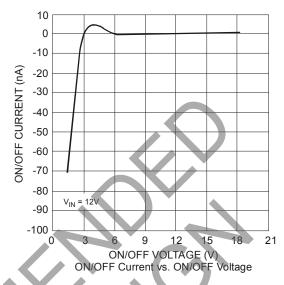


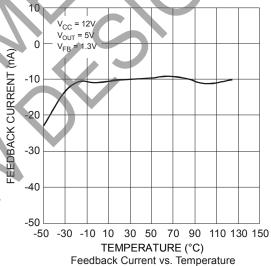
### Typical Characteristics (continued)













### **Application Information**

#### Pin Functions

#### +V<sub>IN</sub>

This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be present at this pin to minimize voltage transients and to supply the switching currents needed by the regulator.

#### Ground

Circuit ground.

#### Output

Internal switch. The voltage at this pin switches between  $(+V_{IN} - V_{SAT})$  and approximately -0.5V with a duty cycle of approximately  $V_{OUT}/V_{IN}$ . To minimize coupling to sensitive circuitry, the PCB copper area connected to this pin must be kept at a minimum.

#### Feedback (FB)

Senses the regulated output voltage to complete the feedback loop.

#### ON/OFF (SD)

Allows the switching regulator circuit to be shutdown using logic level signals thus dropping the total input supply current to approximately 150µA. Pulling this pin below a threshold voltage of approximately 1.3V turns the regulator on, and pulling this pin above 1.3V (up to a maximum of 18V) shuts the regulator down. If this shutdown feature is not required, the ON/OFF pin can be wired to the ground pin.

#### **Thermal Considerations**

The TO252-5 surface mount package tab is designed to be soldered to the copper on a PCB. The copper and the board are the heat sink for this package and the other heat producing components, such as the catch diode and inductor. The PCB copper area that the package is soldered to should be at least 0.8 in<sup>2</sup> and ideally should have two or more square inches of 2oz additional copper area, which improves the thermal characteristics. With copper areas greater than approximately 6in<sup>2</sup>, only small improvements in heat dissipation are realized. If further thermal improvements are required, double sided, multi-layer PCBs with large copper areas and/or airflow are recommended.

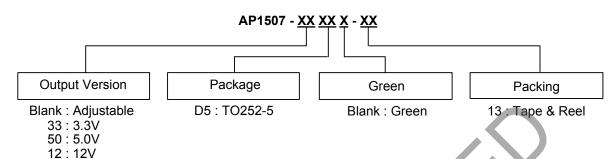
The AP1507 (TO252-5 package) junction temperature rises above ambient temperature with a 3A load for various input and output voltages. This data was taken with the circuit operating as a buck-switching regulator with all components mounted on a PCB to simulate the junction temperature under actual operating conditions. This curve can be used for a quick check for the approximate junction temperature for various conditions, but there are many factors that can affect the junction temperature. When load currents higher than 3A are used, double-sided or multi-layer PCBs with large copper areas and/or airflow might be required, especially for high ambient temperatures and high output voltages.

For the best thermal performance, wide copper traces and generous amounts of PCB copper should be used in the board layout. One exception to this is the output (switch) pin, which should not have large areas of copper. Large areas of copper provide the best transfer of heat (lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further.

Package thermal resistance and junction temperature rise numbers are all approximate, and there are many factors that will affect these numbers. Some of these factors include board size, shape, thickness, position, location, and even board temperature. Other factors are trace width, total PC copper area, copper thickness, single- or double-sided, multi-layer board, and the amount of solder on the board. The effectiveness of the PCB to dissipate heat also depends on the size, quantity, and spacing of other components on the board, as well as whether the surrounding air is still or moving. Furthermore, some of these components, such as the catch diode, add heat to the PCB, and the heat can vary as the input voltage changes. Depending on the physical size, type of core material, and the DC resistance, the inductor can either act as a heat sink taking heat away from the board, or it could add heat to the board.



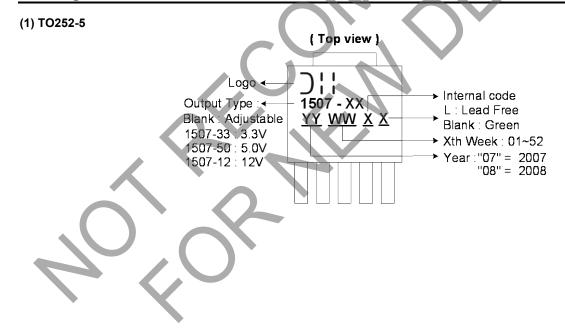
### **Ordering Information**



	Voltage	Bookaga	Backage	Lead		Part N	umber Suffix	
Device	(V)	Package Code	Package (Note 5)		Quantity	Tube	13" Tape and Reel	Status
AP1507-12D5-13	12	K5	TO252-5	Green	800	NA	-13	End of Life
AP1507-33D5-13	3.3	K5	TO252-5	Green	800	NA	-13	End of Life
AP1507-50D5-13	5.0	K5	TO252-5	Green	800	NA	-13	End of Life
AP1507-D5-13	ADJ	K5	TO252-5	Green	800	NA	-13	NRND

Notes: 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## **Marking Information**

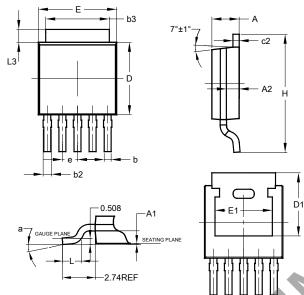




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



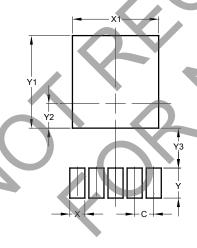


TO252-5						
Dim	Min	Max	Тур			
Α	2.19	2.39	2.29			
<b>A</b> 1	0.00	0.13	0.08			
<b>A2</b>	0.97	1.17	1.07			
b	0.51	0.71	0.583			
b2	0.61	0.79	0.70			
b3	5.21	5.46	5.33			
c2	0.45	0.58	0.531			
D	6.00	6.20	6.10			
D1	5.21	_	_			
е	f	_	1.27			
П	6.45	6.70	6.58			
Ţ	4.32	_				
Н	9.40	10.41	9.91			
F	1.40	1.78	1.59			
L3	0.88	1.27	1.08			
а	0°	10°				
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252-5



Dimensions	Value
Dilliensions	(in mm)
С	1.27
Х	1.00
X1	5.73
Υ	2.00
Y1	6.17
Y2	1.64
Y3	2 66



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